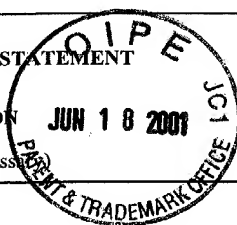


FORM 1449* INFORMATION DISCLOSURE STATEMENT IN AN APPLICATION (Use several sheets if necessary)	Docket Number: 10873.447USD1	Application Number: 09/842,487
	Applicant: Ono et al.	
	Filing Date: April 25, 2001	Group Art Unit: Unknown



U.S. PATENT DOCUMENTS							
EXAMINER INITIAL	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
JMM	US 6,001,724	Dec. 1999	Stansbury				
	US 5,994,212	Nov. 1999	Arakawa et al.				
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FOREIGN PATENT DOCUMENTS							
	DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							



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EXAMINER <i>[Signature]</i>	DATE CONSIDERED <i>4/21/02</i>
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INFORMATION DISCLOSURE STATEMENT

IN AN APPLICATION

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Docket Number:

10873.447USD1

Application Number:

Unknown

Applicant: ONO et al.

Filing Date: April 25, 2001

Group Art Unit: 2812

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04/25/01

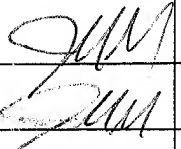
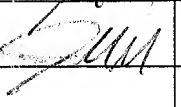
U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	Publication (partial): 7 th Electron Device Reliability Symposium; November, 1997; Pages 89-94, "The effect of stud bumping about the MOSFETs on Device Reliability" by N. Shimoyama, et al., NTT System Electronics Laboratories
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EXAMINER

DATE CONSIDERED

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